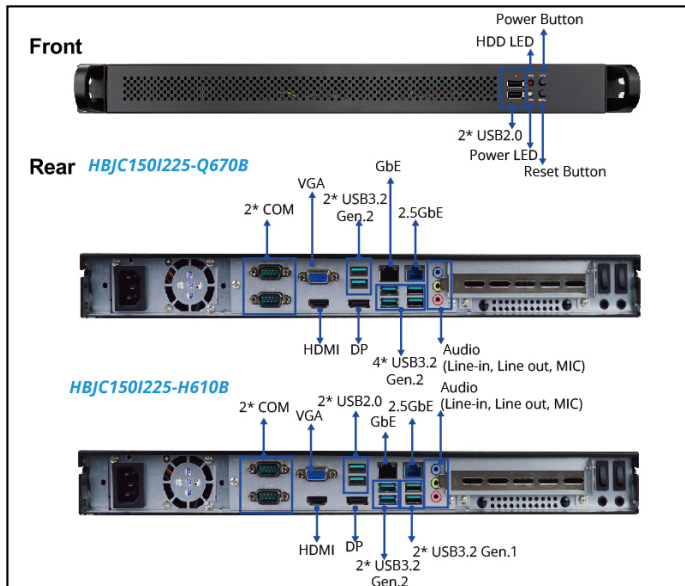


1U Rackmount: Supports Intel® LGA 1700 Socket for 12th, 13th, and 14th Gen Processors, with Up to 96GB DDR5 RAM



Features

- Supports Intel® 12th/13th/14th Gen Processors: LGA1700 Socket (Max 65W TDP).
- Support Intel® LGA1700 12/13/14th Gen Socket Processor (Formerly Alder Lake-S, TDP 65W)
- DDR5 Memory: 2x 4800MHz/5600MHz SO-DIMM up to 96GB.
- Triple Display Support: 1x DP, 1x HDMI, 1x VGA.
- Dual Ethernet Ports: 1GbE and 2.5GbE for faster networking
- Comprehensive I/O: 8x USB, 1x MIC, 1x Line-out, 1x Line-in, 2x COM
- Onboard TPM 2.0 (optional): Enhanced data security.
- 1U FLEX 400W Power Supply: Efficient power for rackmount systems.

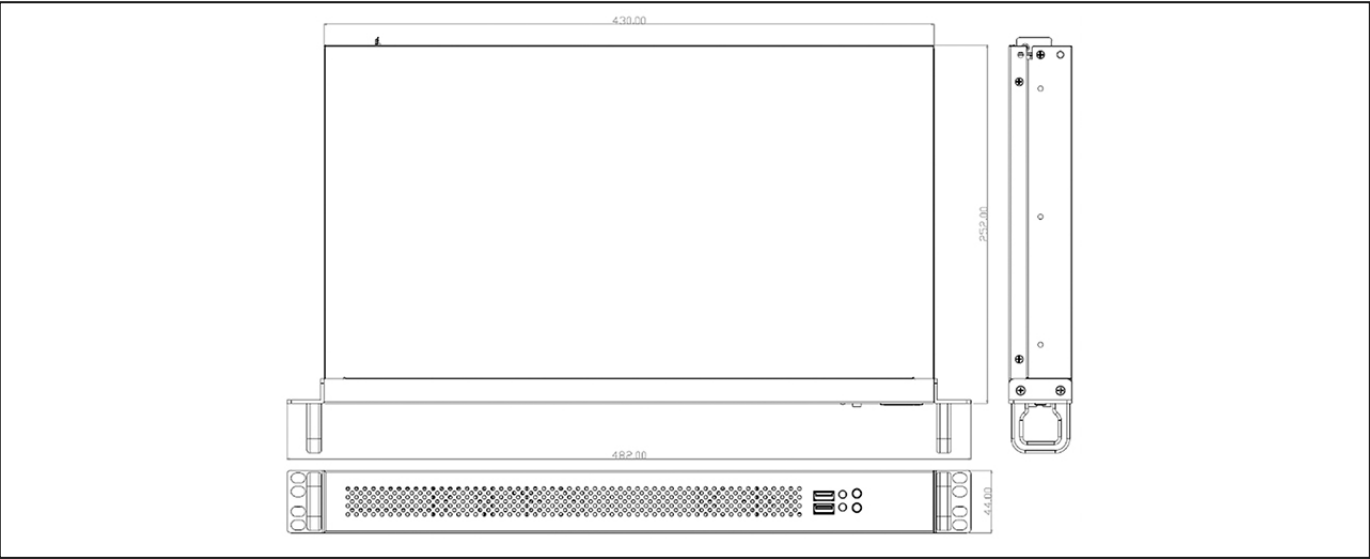
Packing List

PART NUMBER	DESCRIPTION	QTY
Change according to shipping area	Power Cord	1
LCSCJC150-F	Screw Pack	1
G01-SATA3-BL-1F	SATA Cable	1
F07-FN9025-F	90x25mm LGA1700 CPU FAN Module	1

Specifications

SYSTEM	
MB FORM FACTOR	Mini-ITX
CPU	Intel® LGA1700 12/13/14th Gen Socket Processor (Formerly Alder Lake-S, TDP 65W)
CHIPSET	Intel® Q670E/H610/H610E
MEMORY	2 x DDR5 4800MHz SO-DIMM, up to 96GB 2 x DDR5 5600MHz SO-DIMM, up to 64GB (Intel® 13th/14th Gen CPU)
BIOS	AMI Flash ROM
SECURITY	TPM2.0
RTC BATTERY	Lithium Battery
OS SUPPORT	Windows® 11 (64bit) Linux
POWER	
POWER REQUIREMENT	ATX Power Supply 1U FLEX 400W ATX PWR (4+24 pin)
POWER ON MODE	ATX (Default) Mode
DISPLAY	
GPU	Intel® UHD Graphics
DP	1 x DP1.4a (Max Resolution: 4096 x 2304@60Hz)
HDMI	1 x HDMI 2.0b (Max Resolution: 4096 x 2160@60Hz)
VGA	1 x VGA (Max Resolution: 1920 x 1080 @60Hz)
MULTIPLE DISPLAY	Support 3 Displays
AUDIO	
CODEC	Realtek Audio Codec
LAN	
ETHERNET	1 x Intel® i219-LM GbE + 1 x Intel® i225-V 2.5GbE (Q670) 1 x Intel® i219-V GbE + 1 x Intel® i225-V 2.5GbE (H610)
SYSTEM I/O	
REAR PANEL I/O	2 x RJ45 6 x USB 3.2 Gen.2 (HBJC150I225-Q670) 4 x USB 3.2 Gen.2 + 2 x USB2.0 (HBJC150I225-H610) 1 x HDMI 1 x DP 1 x VGA 2 x COM 1 x Line-in 1 x Line-out 1 x MIC-in
FRONT PANEL I/O	1 x Power Button 1 x Reset Button 2 x USB 2.0 1 x Power LED 1 x HDD LED
STORAGE	
SATA	2 x SATA III (6 Gb/s) 2.5" Device, (HBJC150I225-Q670 support RAID 0, 1)
EXPANSION	
M.2	1 x M-key 2280 (PCIe Gen.3 x4 interface) support NVMe 1 x M-Key 2242 (PCIe Gen.4 x4/SATA interface) support NVMe (HBJC150I225-Q670 only) 1 x E-Key 2230 (USB 2.0/PCIe 3.0 x1) Support CNVi 1 x B-key 3042 (PCIe Gen.3 x1/USB3.2 Gen.2/USB2.0 interface) (HBJC150I225-Q670 only) 1 x B-key 3042 (PCIe Gen.3 x1 interface) (HBJC150I225-H610 only)
PCIe	1 x PCI Express x16 (Gen.4)
SIM	1 x SIM Card Slot
OTHERS	
OTHER	1 x GPIO (8 Bit)
MECHANICAL	
DIMENSIONS (W x D x H)	430.0 (W) x 252.0 (D) x 44.0 (H) mm
GROSS WEIGHT	5.2 kg
NET WEIGHT	4.2 kg
ENVIRONMENT & CERTIFICATION	
SHOCK	15G, 11ms duration
VIBRATION	1 Grms/ 5- 500Hz/ Operation
OPERATING TEMPERATURE	0°C ~ 50°C (32°F ~ 122°F)
STORAGE TEMPERATURE	-40°C ~ 85°C (-40°F ~ 185°F)
OPERATING HUMIDITY	10 ~ 90% @ 40°C, Non-condensing
CERTIFICATION	CE/FCC Class A LVD
ESG DECLARATION	EU RoHS China RoHS ErP

DimensionUnit: mm



Ordering Information

PART NUMBER	HBJC150I225-Q670BA1	HBJC150I225-H610BA1
CPU	Intel® Socket LGA1700 CPU	Intel® Socket LGA1700 CPU
POWER REQUIREMENT	ATX Power Supply	ATX Power Supply
GPU	Intel® UHD Graphics	Intel® UHD Graphics
DP	1 x DP	1 x DP
HDMI	1 x HDMI	1 x HDMI
VGA	1 x VGA	1 x VGA
MULTIPLE DISPLAY	Support 3 Displays	Support 3 Displays
ETHERNET	2 x GbE	2 x GbE
I/O	2 x RJ45	2 x RJ45
I/O	6 x USB 3.2 Gen 2	6 x USB 3.2 Gen 2
I/O	2 x USB 2.0	2 x USB 2.0
I/O	1 x HDMI	1 x HDMI
I/O	1 x DP	1 x DP
I/O	1 x VGA	1 x VGA
I/O	2 x COM	2 x COM
I/O	1 x Line-in	1 x Line-in
I/O	1 x Line-out	1 x Line-out
I/O	1 x MIC-in	1 x MIC-in
I/O	1 x Power Button	1 x Power Button
I/O	1 x Reset	1 x Reset
I/O	1 x Power LED	1 x Power LED
I/O	1 x HDD LED	1 x HDD LED
SATA	2 x SATA III	2 x SATA III
M.2	1 x M-Key 2242	1 x M-Key 2242
M.2	1 x M-Key 2280	1 x M-Key 2280
M.2	1 x E-Key 2230	1 x E-Key 2230
PCIe	1 x PCIe x16	1 x PCIe x16
OPERATING TEMPERATURE	0°C ~ 50°C (32°F ~ 122°F)	0°C ~ 50°C (32°F ~ 122°F)